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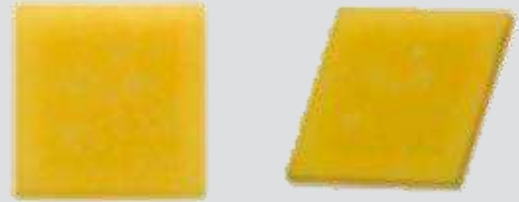
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Middle Power LED Series Flip Chip Package

LM101A



LM101A opens up a new world of lighting design with its high output and small form factors



Features & Benefits

- Greater freedom of design with compact package size
- High degree of reliability with plastic-free structure
- Low thermal resistance
- High efficiency providing optimized solution
- Compact footprint (1.15 x 1.15 mm)

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1. Characteristics

a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Operating Temperature	T_a	-40 ~ +85	°C	-
Storage Temperature	T_{stg}	-40 ~ +120	°C	-
LED Junction Temperature	T_j	125	°C	-
Forward Current	I_F	450	mA	-
Assembly Process Temperature	-	260 <10	°C s	-
ESD (HBM)	-	±2	kV	-

b) Electro-optical Characteristics ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

Item	Unit	Rank	Bin	Min.	Typ.	Max.
Forward Voltage (V_F)	V	6E	6A	2.7	-	2.9
			AE	2.9	-	3.1
Reverse Voltage (@ $-10 \mu\text{A}$)	V			-10.0	-	-
Color Rendering Index (R_a)	-	8		80	-	-
Special CRI (R9)	-			0	-	-
Thermal Resistance (junction to chip point)	K/W			-	2	-
Beam Angle	$^\circ$			-	150	-

Note: Samsung maintains measurement tolerance of : Forward voltage = $\pm 0.1 \text{ V}$, Luminous flux = $\pm 5 \%$, CRI = ± 3 , R9 = ± 6.5

c) Luminous Flux Characteristics ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

Item	CRI	Nominal CCT (K)	SY		SZ		SA		SB		SC		SD		SE		SF		SG		
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
			35	39	39	43	43	47	47	51	51	55	55	59	59	63	63	67	67	71	71
Luminous Flux (Φ_v)	70	3000																			
		3500																			
		4000																			
		5000																			
		5700																			
		6500																			
	80	2700																			
		3000																			
		3500																			
		4000																			
		5000																			
		5700																			
	90	6500																			
		2700																			
		3000																			
			3500																		

Note:

- 1) The LM101A is tested in pulsed condition at rated test current (10 ms pulse width)
- 2) Calculated flux values are for reference only
- 3) Samsung maintains measurement tolerance of: luminous flux = $\pm 5\%$

2. Product Code Information (I_f = 150 mA, T_s = 85 °C)

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	C	P	8	W	T	7	8	H	P	L	1	W	L	S	0	6	E

Digit	PKG Information	Code	Specification
1 2 3	Samsung Chip	SCP	
4	CRI	7 8 9	Min. 70 Min. 80 Min. 90
5	CCT (K)	W V U T R Q P	2700 3000 3500 4000 5000 5700 6500
6	Chip Shape	T	Square
7 8 9	Chip Size (μm)	78H	780x780x170μm
10 11 12	Product Purpose	PL1	PoC for Lighting
13	CCT (K)	W V U T R Q P	2700K 3000K 3500K 4000K 5000K 5700K 6500K
14	MacAdam Step	L U	Single Bin for MacAdam 5-step L(MacAdam 5-step Bin) Single Bin for MacAdam 3-step U(MacAdam 3-step Bin)
15 16	Luminous Flux (lm)	S0	Bin Code: SY, SZ, SA, SB, SC, SD, SE, SF, SG
17 18	Forward Voltage (V)	6E	2.7~3.1 Bin Code: 6A 2.7~2.9 AE 2.9~3.1

a) Luminous Flux Bins ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ °C}$)

CRI (R _a) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range (Φ_v , lm)
70	3000	SCP7VT78HPL1V☆S06E	SD	55 ~ 59
			SE	59 ~ 63
			SF	63 ~ 67
	3500	SCP7UT78HPL1U☆S06E	SD	55 ~ 59
			SE	59 ~ 63
			SF	63 ~ 67
	4000	SCP7TT78HPL1T☆S06E	SE	59 ~ 63
			SF	63 ~ 67
			SG	67 ~ 71
	5000	SCP7RT78HPL1R☆S06E	SE	59 ~ 63
			SF	63 ~ 67
			SG	67 ~ 71
	5700	SCP7QT78HPL1Q☆S06E	SE	59 ~ 63
			SF	63 ~ 67
			SG	67 ~ 71
	6500	SCP7PT78HPL1P☆S06E	SE	59 ~ 63
			SF	63 ~ 67
			SG	67 ~ 71

Note: “☆” can be “L” (Single bin for MacAdam 5-step), “U” (Single bin for MacAdam 3-step)

a) Luminous Flux Bins ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

CRI (R _a) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range (Φ_v , lm)
80	2700	SCP8WT78HPL1W☆S06E	SB	47 ~ 51
			SC	51 ~ 55
			SD	55 ~ 59
			SC	51 ~ 55
			SD	55 ~ 59
			SE	59 ~ 63
	3000	SCP8VT78HPL1V☆S06E	SC	51 ~ 55
			SD	55 ~ 59
			SE	59 ~ 63
			SC	51 ~ 55
			SD	55 ~ 59
			SE	59 ~ 63
	3500	SCP8UT78HPL1U☆S06E	SC	51 ~ 55
			SD	55 ~ 59
			SE	59 ~ 63
			SD	55 ~ 59
			SE	59 ~ 63
			SF	63 ~ 67
	4000	SCP8TT78HPL1T☆S06E	SD	55 ~ 59
			SE	59 ~ 63
			SF	63 ~ 67
			SD	55 ~ 59
			SE	59 ~ 63
			SF	63 ~ 67
5000	SCP8RT78HPL1R☆S06E	SC	51 ~ 55	
		SD	55 ~ 59	
		SE	59 ~ 63	
		SF	63 ~ 67	
		SC	51 ~ 55	
		SD	55 ~ 59	
5700	SCP8QT78HPL1Q☆S06E	SE	59 ~ 63	
		SC	51 ~ 55	
		SD	55 ~ 59	
		SE	59 ~ 63	
		SC	51 ~ 55	
		SD	55 ~ 59	
6500	SCP8PT78HPL1P☆S06E	SD	55 ~ 59	
		SE	59 ~ 63	

Note: “☆” can be “L” (Single bin for MacAdam 5-step) “U” (Single bin for MacAdam 3-step)

a) Luminous Flux Bins ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

CRI (R _a) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range (Φ_v , lm)
90	2700	SCP9WT78HPL1W☆S06E	SY	35 ~ 39
			SZ	39 ~ 43
			SA	43 ~ 47
	3000	SCP9VT78HPL1V☆S06E	SY	35 ~ 39
			SZ	39 ~ 43
			SA	43 ~ 47
3500	SCP9UT78HPL1U☆S06E	SA	43 ~ 47	
		SB	47 ~ 51	

Note: “☆” can be “L” (Single bin for MacAdam 5-step), “U” (Single bin for MacAdam 3-step)

b) Color Bins ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ °C}$)

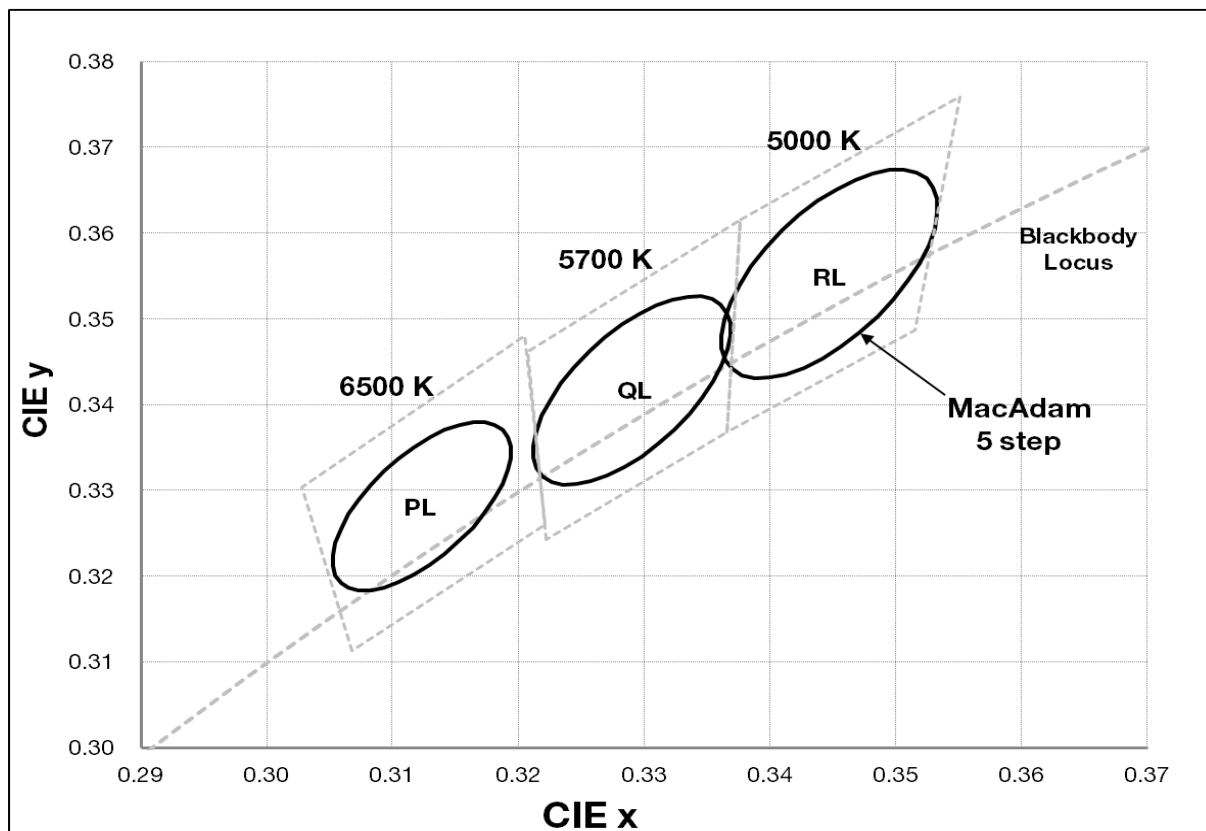
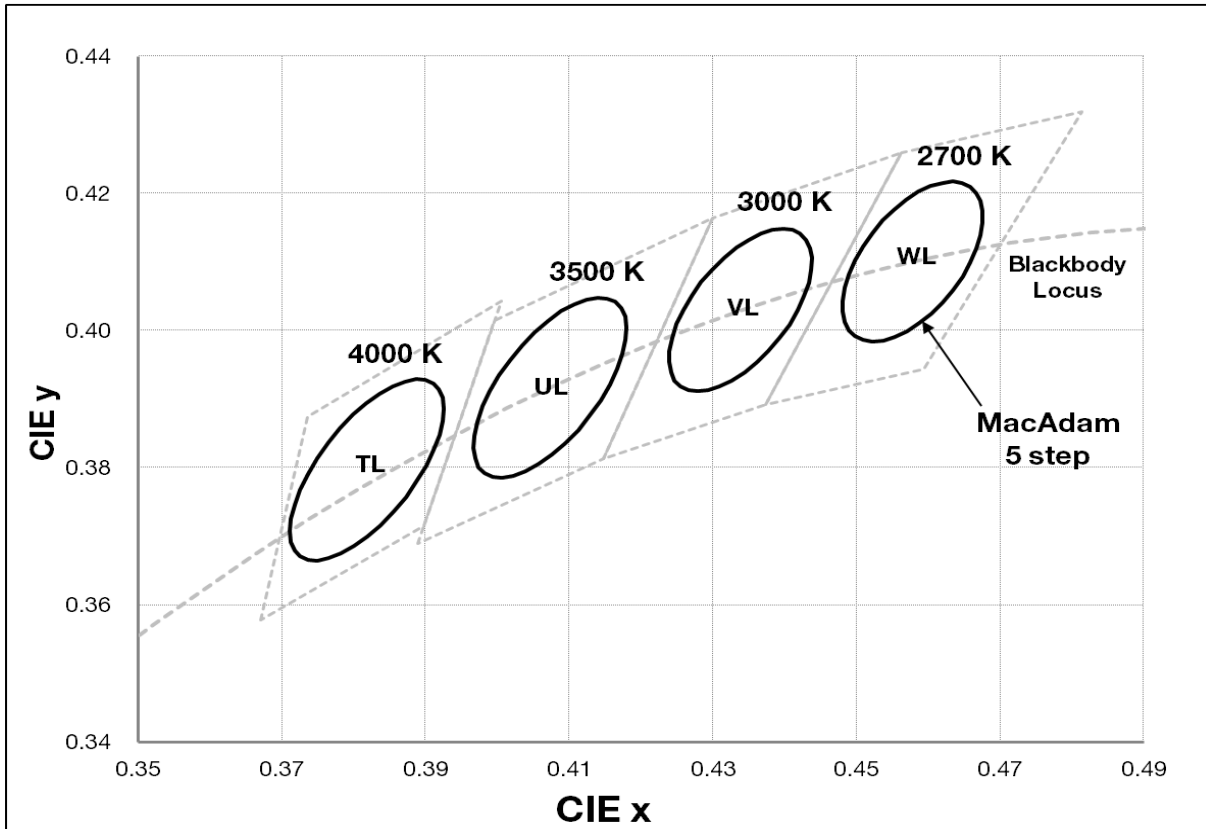
CRI Min.	Nominal CCT (K)	Product Code	Color Rank	Chromaticity Bins	
70	3000	SCP7VT78HPL1V☆ S06E	VL	VL	
			VU	VU	
	3500	SCP7UT78HPL1U☆ S06E	UL	UL	
			UU	UU	
	4000	SCP7TT78HPL1T☆ S06E	TL	TL	
			TU	TU	
	5000	SCP7RT78HPL1R☆ S06E	RL	RL	
			RU	RU	
	5700	SCP7QT78HPL1Q☆ S06E	QL	QL	
			QU	QU	
	6500	SCP7PT78HPL1P☆ S06E	PL	PL	
			PU	PU	
	80	2700	SCP8WT78HPL1W☆ S06E	WL	WL
				WU	WU
3000		SCP8VT78HPL1V☆ S06E	VL	VL	
			VU	VU	
3500		SCP8UT78HPL1U☆ S06E	UL	UL	
			UU	UU	
4000		SCP8TT78HPL1T☆ S06E	TL	TL	
			TU	TU	
5000		SCP8RT78HPL1R☆ S06E	RL	RL	
			RU	RU	
5700		SCP8QT78HPL1Q☆ S06E	QL	QL	
			QU	QU	
6500		SCP8PT78HPL1P☆ S06E	PL	PL	
			PU	PU	
90	2700	SCP9WT78HPL1W☆ S06E	WL	WL	
			WU	WU	
	3000	SCP9VT78HPL1V☆ S06E	VL	VL	
			VU	VU	
	3500	SCP9UT78HPL1U☆ S06E	UL	UL	
			UU	UU	

Note: “☆” can be “L” (Single bin for MacAdam 5-step), “U” (Single bin for MacAdam 3-step)

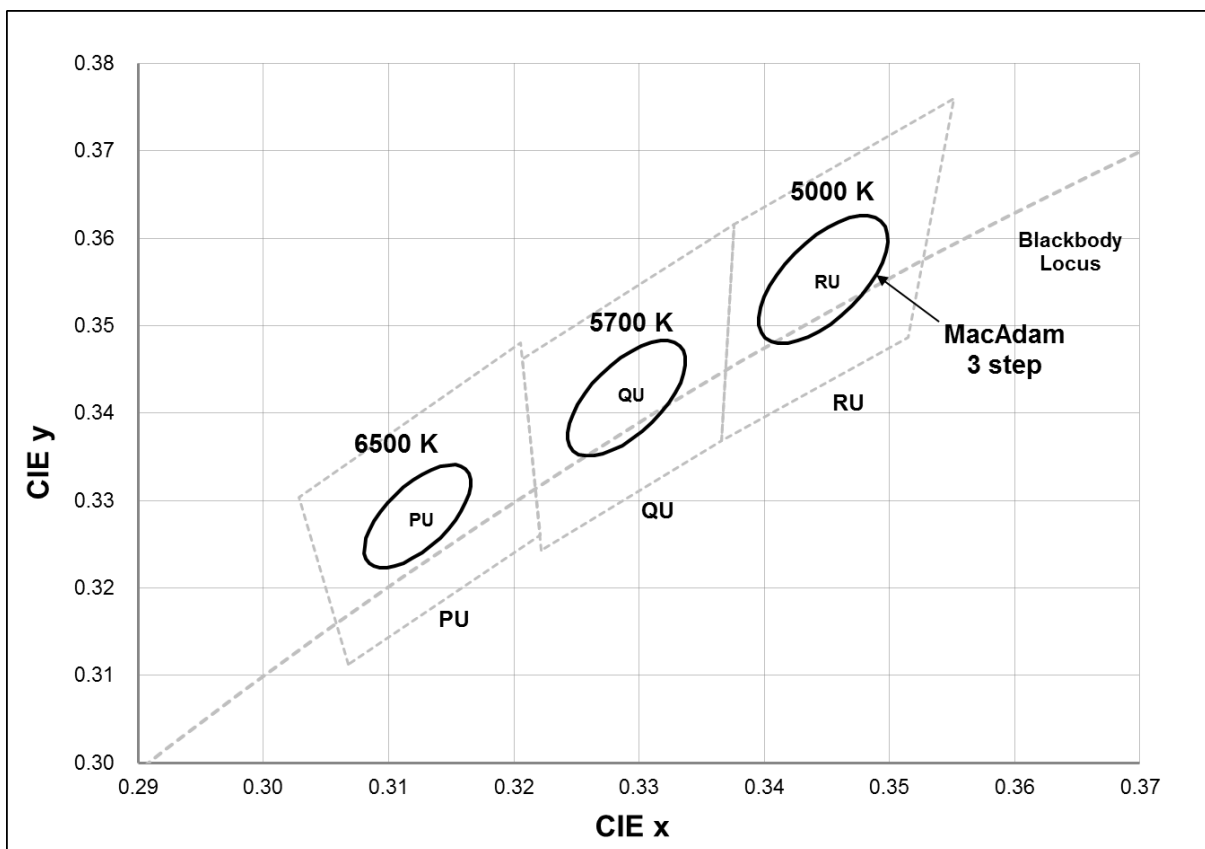
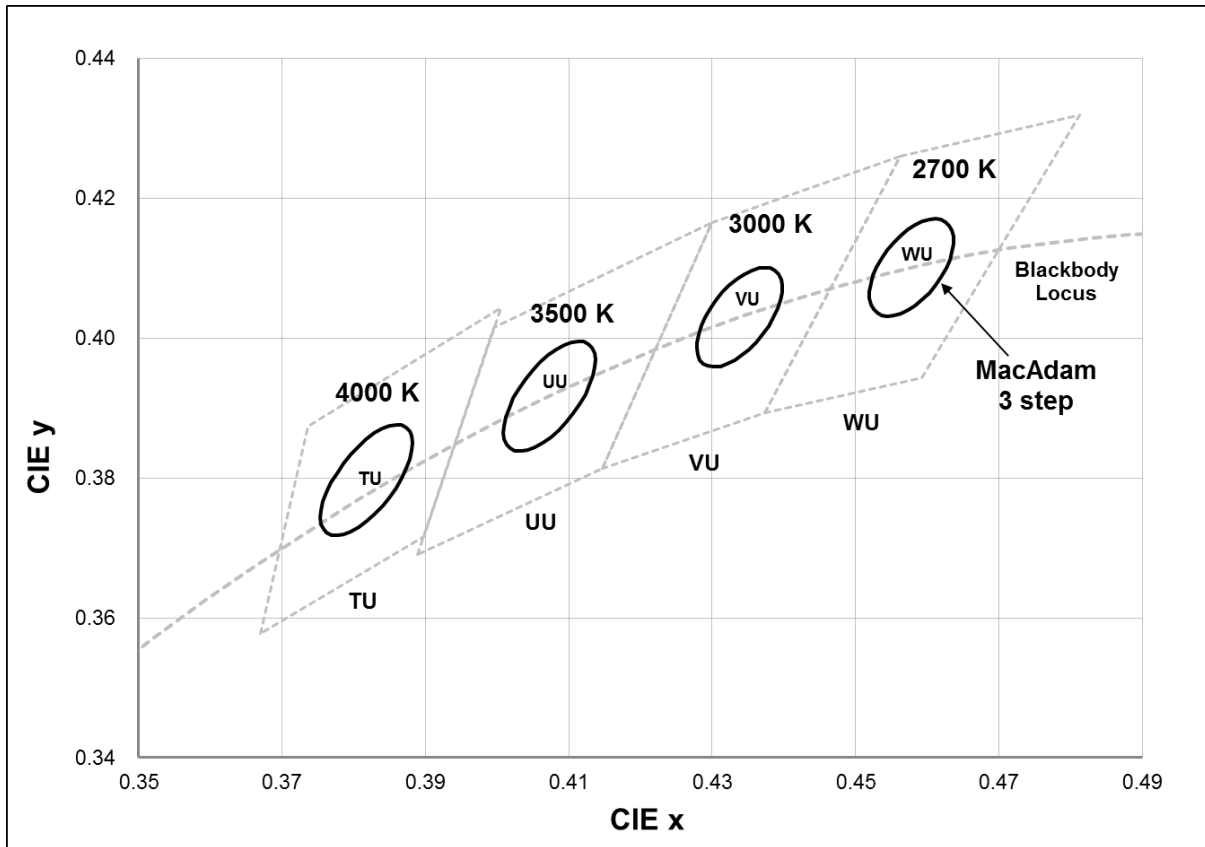
c) Voltage Bins ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

Nominal CCT (K)	CRI Min.	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
			6E	6A	2.7 ~ 2.9
				AE	2.9 ~ 3.1

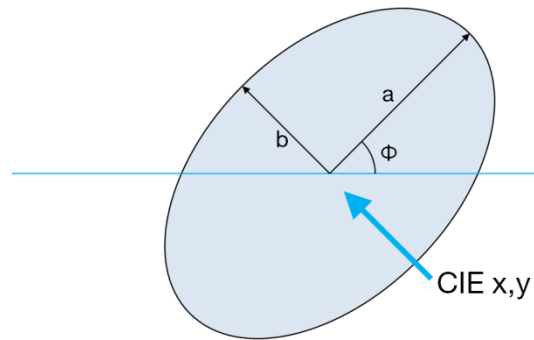
d) Chromaticity Region & Coordinates ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$) : "L" (Single bin for MacAdam 5-step)



d) Chromaticity Region & Coordinates ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$) : "U" (Single bin for MacAdam 3-step)



d) Chromaticity Region & Coordinates ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)



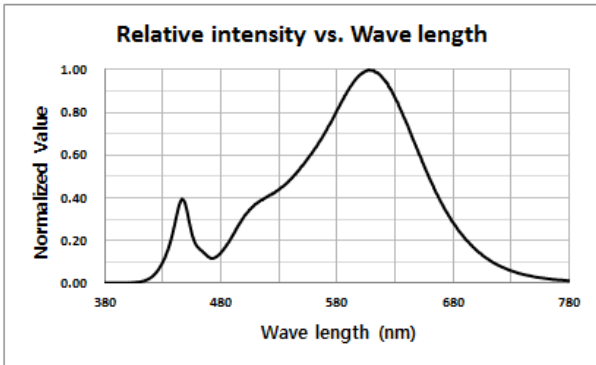
	CCT (K)	Center point		Major-axis	Minor-axis	Rotation
		CIE x	CIE y	a	b	ϕ
3 step (U code)	2700	0.4578	0.4101	0.0081	0.0042	53.70
	3000	0.4338	0.4030	0.0083	0.0041	53.22
	3500	0.4073	0.3917	0.0093	0.0041	54.00
	4000	0.3818	0.3797	0.0094	0.0040	53.72
	5000	0.3447	0.3553	0.0082	0.0035	59.62
	5700	0.3287	0.3417	0.0075	0.0032	59.10
	6500	0.3123	0.3282	0.0067	0.0029	58.57
5 step (L code)	2700	0.4578	0.4101	0.0135	0.0070	53.70
	3000	0.4338	0.4030	0.0138	0.0068	53.22
	3500	0.4073	0.3917	0.0155	0.0068	54.00
	4000	0.3818	0.3797	0.0157	0.0067	53.72
	5000	0.3447	0.3553	0.0137	0.0058	59.62
	5700	0.3287	0.3417	0.0125	0.0053	59.10
	6500	0.3123	0.3282	0.0112	0.0048	58.57

Note: Samsung maintains measurement tolerance of: $C_x, C_y = \pm 0.005$

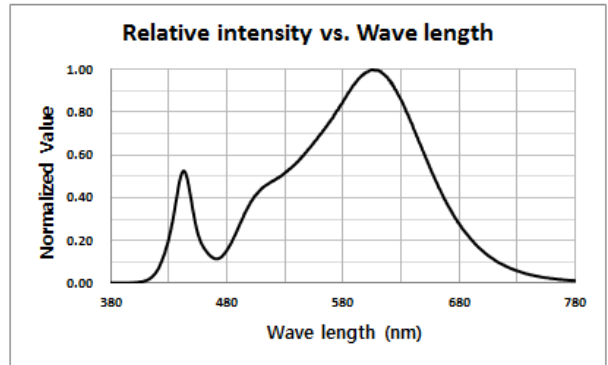
3. Typical Characteristics Graphs

a) Spectrum Distribution ($I_f = 150 \text{ mA}$, $T_s = 25 \text{ }^\circ\text{C}$)

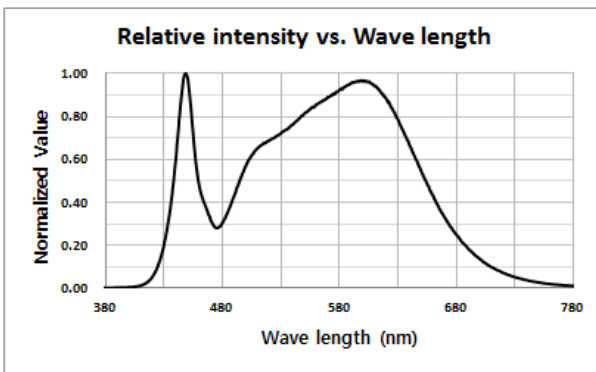
CCT: 2700 K



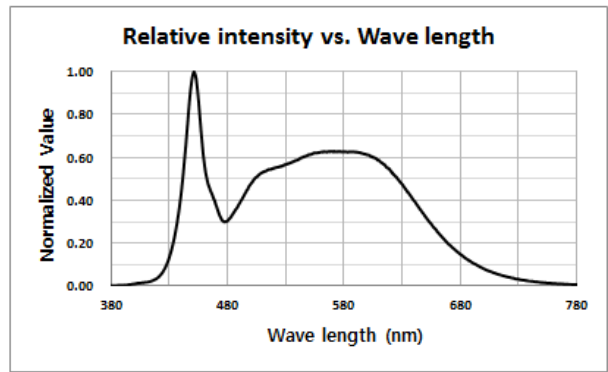
CCT: 3000 K



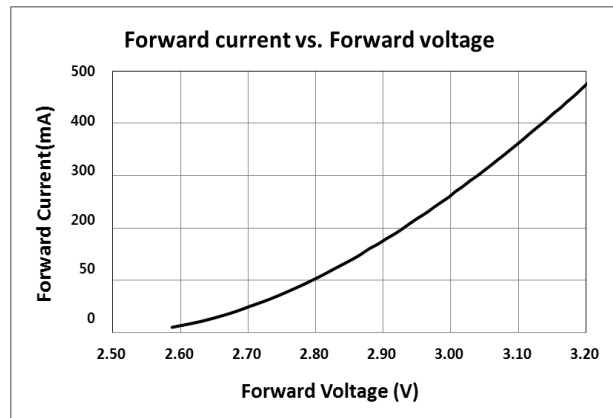
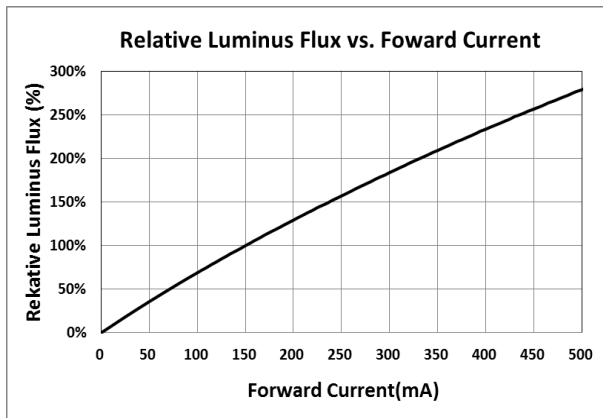
CCT: 4000 K



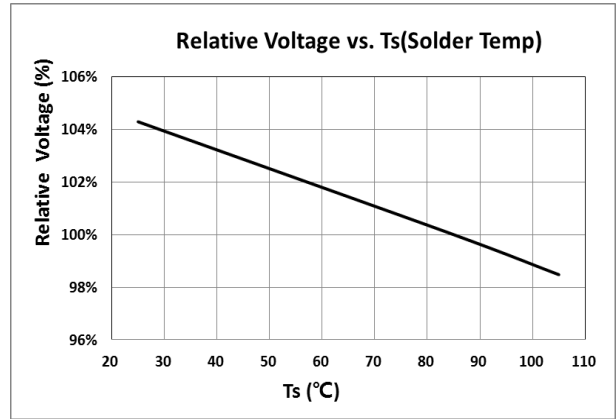
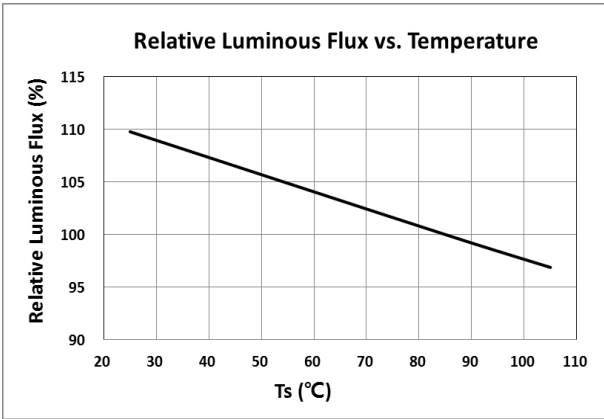
CCT: 5000 K



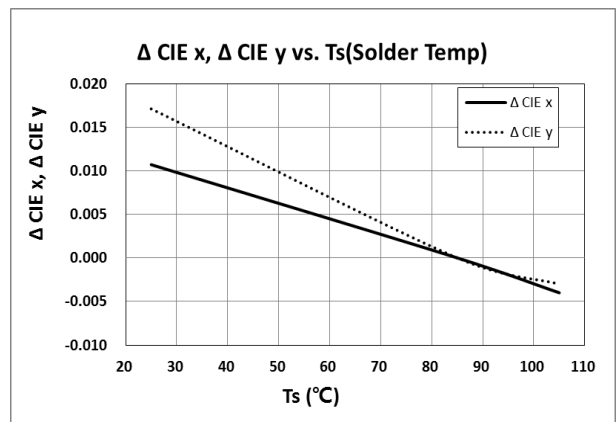
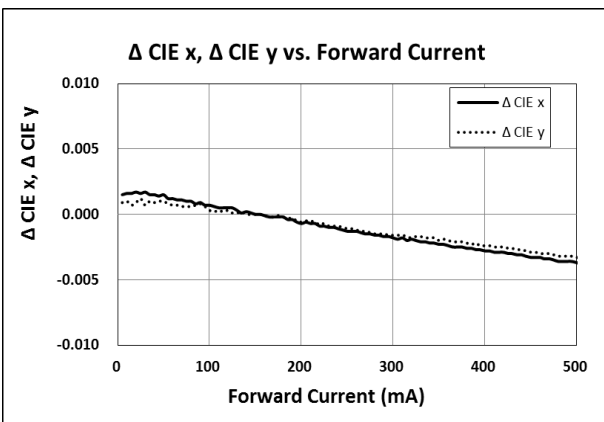
b) Forward Current Characteristics ($T_s = 25 \text{ }^\circ\text{C}$)



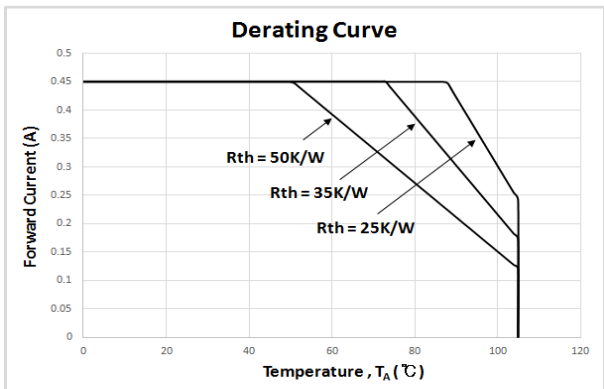
c) Temperature Characteristics ($I_F = 150 \text{ mA}$)



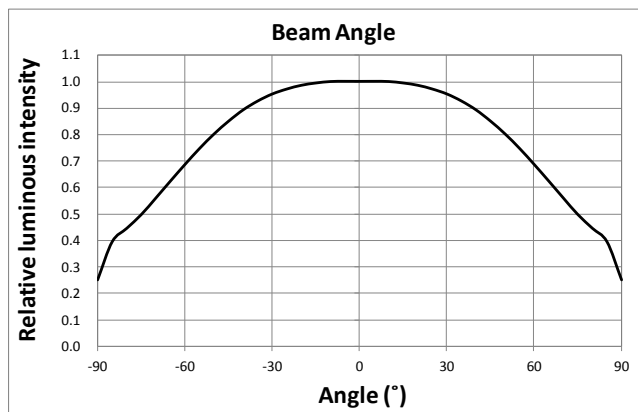
d) Color Shift Characteristics ($T_s = 25 \text{ °C}$, $I_F = 150 \text{ mA}$)



e) Derating Curve

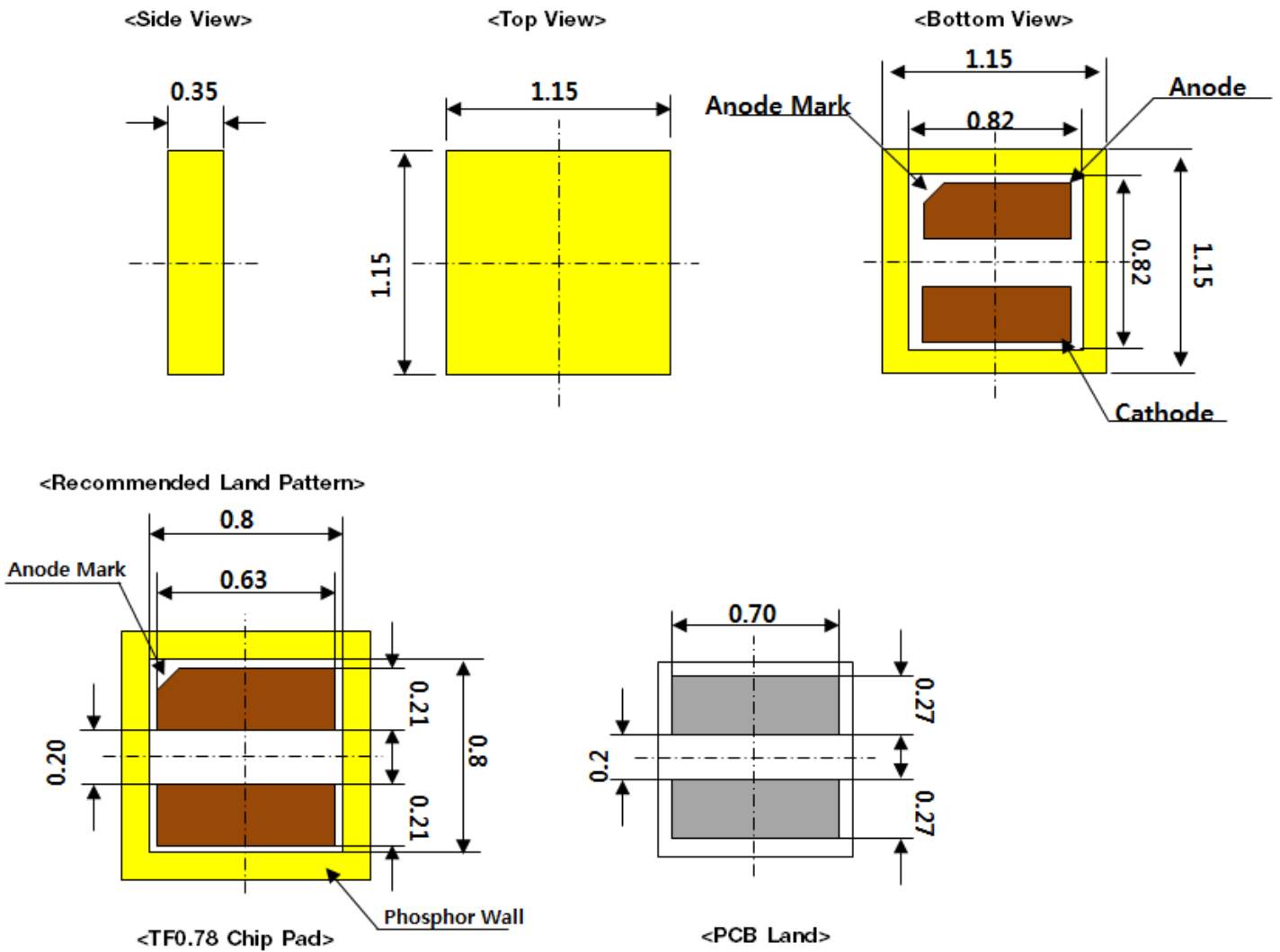


R_{th} is measured after soldering of LED chip on the metal based substrate.
 *metal: aluminum (refer to page 17)

f) Beam Angle Characteristics ($I_F = 150 \text{ mA}$)

4. Outline Drawing & Dimension

1. Tolerance is ± 0.10 mm
2. Do not place LEDs with pressure

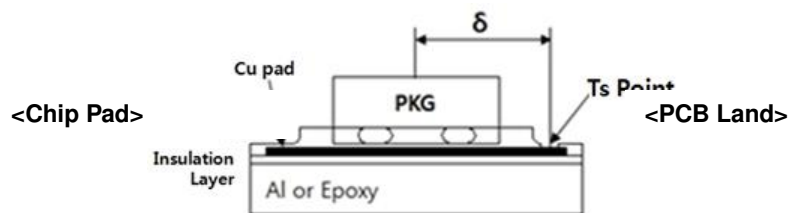


T_s Point & Measurement Method:

Measure nearest point from the center of LED chip (δ) as shown below.

Distance between chip center and T_s point (δ) = 3.5 mm

$$T_j = T_s + \text{Power} \times \text{Thermal resistance at } T_s (R_{j-s})$$

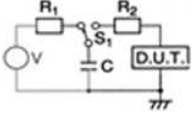


Precautions:

- 1) This LED chip PKG does not contain built-in ESD protection device.
- 2) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 3) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED`s characteristics should be carefully checked before and after such repair.
- 4) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

5. Reliability Test Items & Conditions

a) Test Items

Test Item	Test Condition	Test Hour / Cycle	Sample Size
MSL Test	125 °C 24 h drying → 60 °C, 60 % RH 120 h → 260 °C 10 sec 3 cycles	1 cycle	11
Room Temperature Life Test	25 °C, Derated max current	1000 h	22
High Temperature Life Test	85 °C, Derated max current	1000 h	22
High Temperature Humidity Life Test	85 °C, 85 % RH, Derated max current	1000 h	22
Low Temperature Life Test	-40 °C, DC Derated max current	1000 h	22
Powered Temperature Cycle Test	-45 °C / 20 min ↔ 85 °C / 20 min, sweep 100 min cycle on/off: each 5 min, Derated max current	100 cycles	22
Thermal Shock	-45 °C / 15 min ↔ 125 °C / 15 min → Hot plate 180 °C	800 cycles	100
High Temperature Storage	120 °C	1000 h	11
Low Temperature Storage	-40 °C	1000 h	11
ESD (HBM)	 <p> R_1: 10 MΩ R_2: 1.5 kΩ C: 100 pF V: ± 5 kV </p>	5 times	5
Vibration Test	20~2000~20 Hz, 200 m/s ² , sweep 4 min X, Y, Z 3 direction, each 1 cycle	4 cycles	11
Mechanical Shock Test	1500 g, 0.5 ms	5 cycles	11

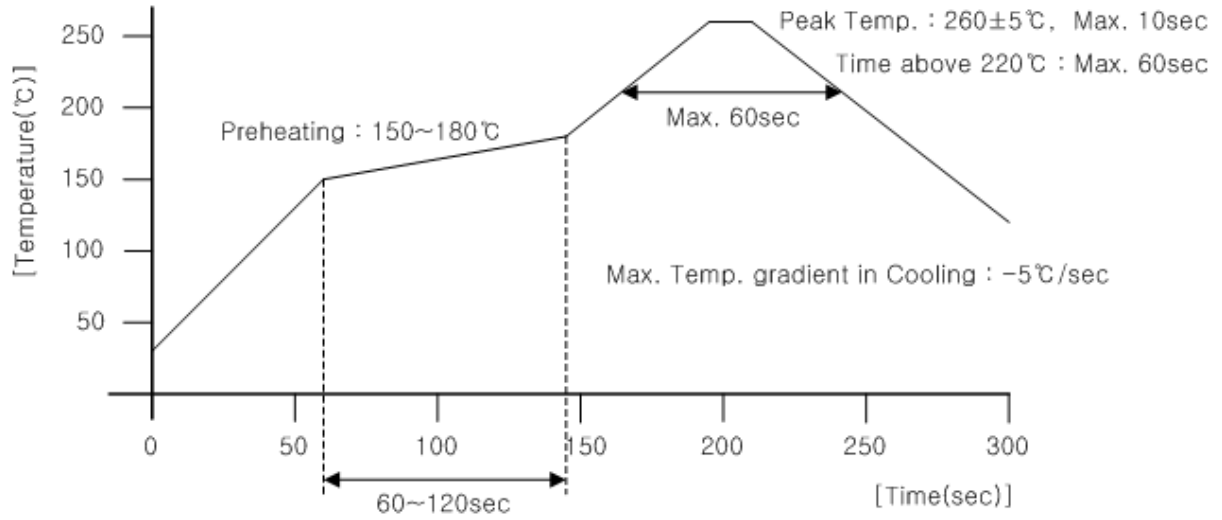
b) Criteria for Judging the Damage

Item	Symbol	Test Condition ($T_s = 25$ °C)	Limit	
			Min	Max
Forward Voltage	V_F	$I_F =$ Derated max current	Init. Value * 0.9	Init. Value * 1.1
Luminous Flux	Φ_v	$I_F =$ Derated max current	Init. Value * 0.7	Init. Value * 1.1

6. Soldering Conditions

a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



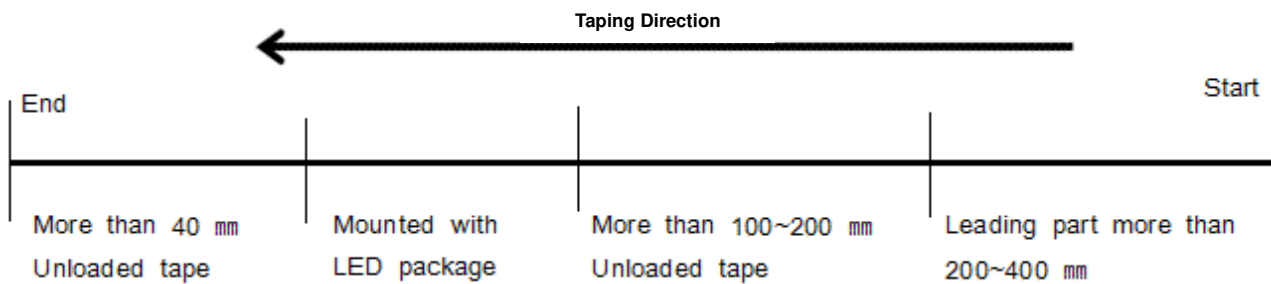
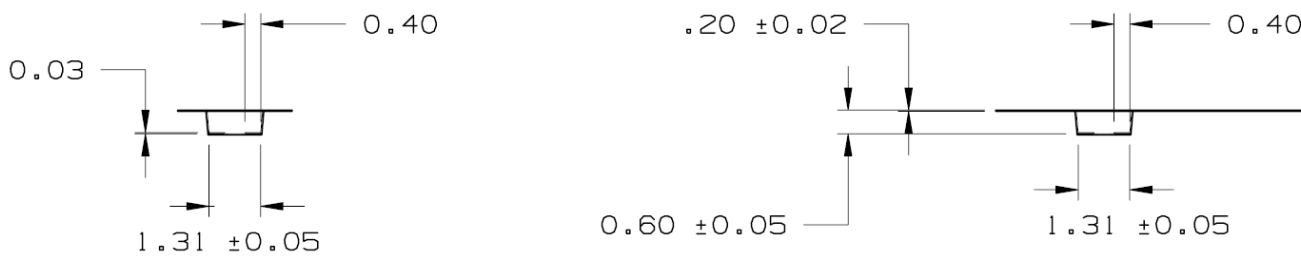
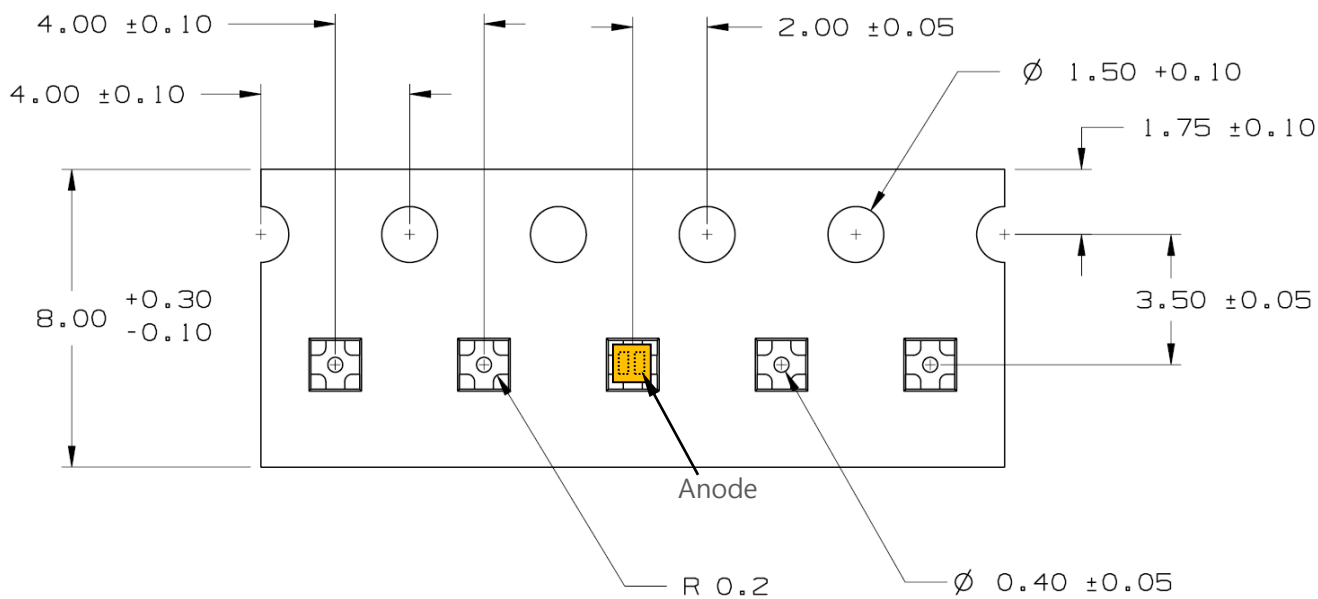
b) Manual Soldering Conditions

Not more than 5 seconds @ max. 300 °C, under soldering iron

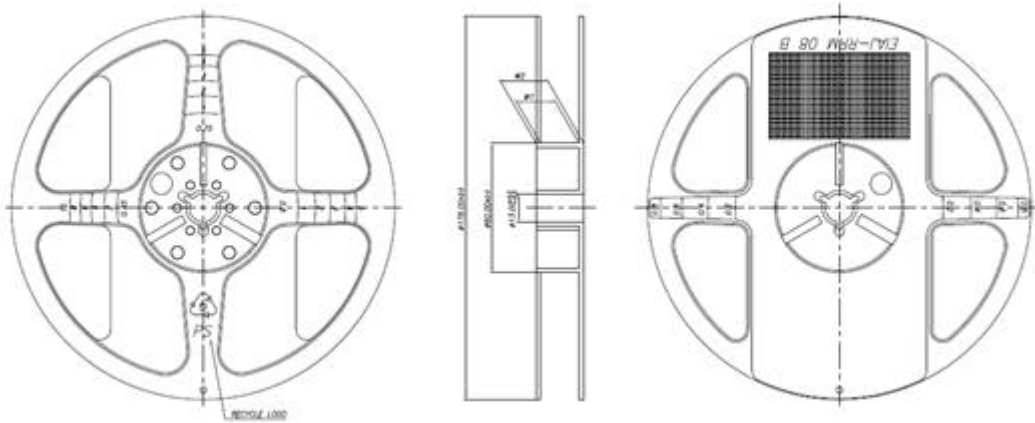
7. Tape & Reel

a) Taping Dimension

(unit: mm)



b) Reel Dimension



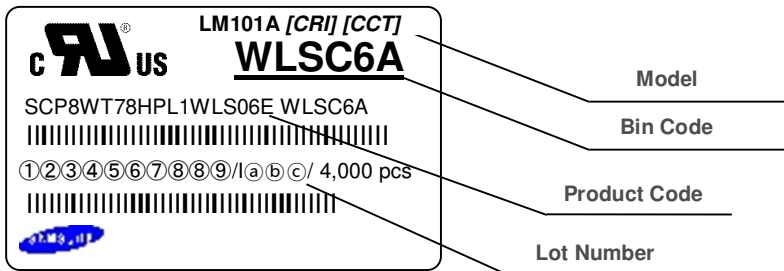
Width	W1	W2
8mm	9 ±0.3	11.9 ±1.0

Notes:

- 1) Quantity: The quantity/reel is 4,000 pcs
- 2) Cumulative Tolerance: Cumulative tolerance / 10 pitches is ± 0.2 mm
- 3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

8. Label Structure

a) Label Structure



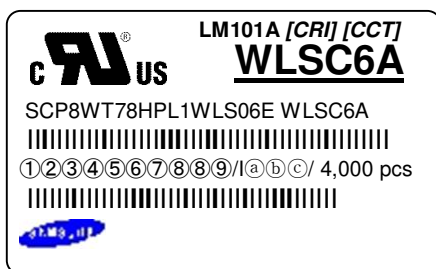
Note: Denoted product code and bin code above is only an example

Bin Code:

- ⒶⒷ: Chromaticity bin (refer to page 10-14)
- ⒸⒹ: Luminous Flux bin (refer to page 7-9)
- ⒺⒻ: Forward Voltage bin (refer to page 11)

b) Lot Number

The lot number is composed of the following characters:



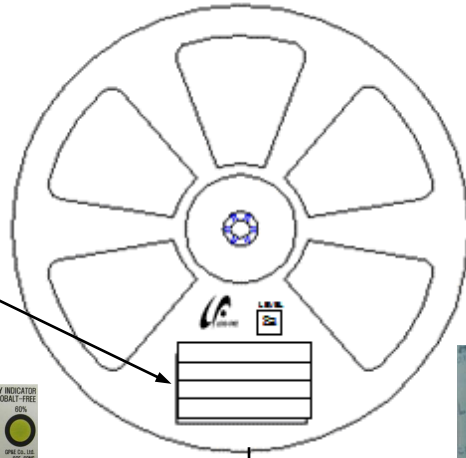
①②③④⑤⑥⑦⑧⑨ / ⒶⒷⒸ / 4,000 pcs

- ①② : Production site (G3: Shenzhen China, G4: Guangzhou China, GB: Nanchang China)
- ③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
- ④ : Year (Y: 2014, Z: 2015, A: 2016 ...)
- ⑤ : Month (1~9, A, B, C)
- ⑥ : Day (1~9, A, B~V)
- ⑦⑧⑨ : Product serial number (001 ~ 999)
- ⒶⒷⒸ : Reel number (001 ~ 999) or (AAA ~ ZZZ)

9. Packing Structure

a) Packing Process

Reel



Aluminum Vinyl Bag



Outer Box

Material: Paper (SW3B(A))

Type	Size (mm)			Note
	L	W	H	
7 inch	245 ± 5	220 ± 5	86 ± 5	Up to 7 reels max.

① Side Label

